



#### 40V 175°C DUAL N-CHANNEL ENHANCEMENT MODE MOSFET

## **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(on)</sub> max	I <sub>D</sub> max T <sub>C</sub> = +25°C
40V	$15m\Omega @ V_{GS} = 10V$	43.6A
400	$25m\Omega @ V_{GS} = 4.5V$	33A

## **Features and Benefits**

- Rated to +175°C—Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switching (UIS) Test in Production Ensures More Reliable and Robust End Application
- High Conversion Efficiency
- Low R<sub>DS(on)</sub>—Minimizes On State Losses
- Low Input Capacitance
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The DMTH4014LPDQ is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.

https://www.diodes.com/quality/product-definitions/

# **Description and Applications**

This MOSFET is designed to meet the stringent requirements of automotive applications. It is qualified to AEC-Q101, supported by a PPAP, and is ideal for use in:

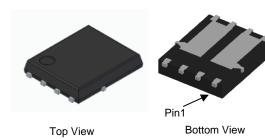
- Backlighting
- Power Management Functions
- DC-DC Converters

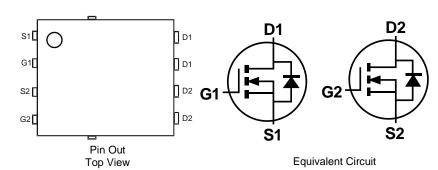
## **Mechanical Data**

- Package: PowerDI<sup>®</sup>5060-8
- Package Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish—Matte Tin Annealed over Copper Leadframe.
   Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.097 grams (Approximate)

Site 1:

PowerDI5060-8 (Type C)

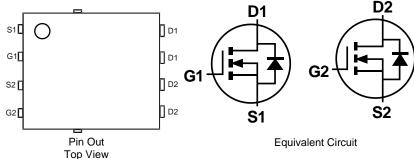




Site 2:

PowerDI5060-8/SWP (Type UXD)







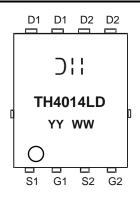
# Ordering Information (Note 4)

Part Number	Package	Packing		
I alt ivuilibei	i ackage	Qty.	Carrier	
DMTH4014LPDQ-13	PowerDI5060-8 (Type C)	2,500	Tape & Reel	
DMTH4014LPDQ-13	PowerDI5060-8/SWP (Type UXD)	2,500	Tape & Reel	

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and 1000ppm antimony compounds.
   For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

# **Marking Information**



);; = Manufacturer's Marking TH4014LD<u>=</u> Product Type Marking Code YYWW or YYWW = Date Code Marking YY or YY = Year (ex: 21 = 2021) WW = Week (01 to 53)



# **Maximum Ratings** (@ T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			$V_{DSS}$	40	V
Gate-Source Voltage			$V_{GSS}$	±20	V
Continuous Drain Current (Note 6) $ T_C = +25^{\circ}C $ $ T_C = +100^{\circ}C $			I <sub>D</sub>	43.6 30.8	А
Continuous Drain Current (Note 5)	Steady State	$T_A = +25$ °C $T_A = +85$ °C $T_A = +100$ °C	I <sub>D</sub>	10.6 7.8 7.5	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%) (Note 6)			I <sub>DM</sub>	174	A
Maximum Continuous Body Diode Forward Current (Note 6)			I <sub>S</sub>	36	A
Avalanche Current, L = 0.3mH			I <sub>AS</sub>	11.7	A
Avalanche Energy, L = 0.3mH			E <sub>AS</sub>	20.5	mJ

# **Thermal Characteristics**

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)	$T_A = +25^{\circ}C$	$P_{D}$	2.4	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\theta JA}$	62.6	°C/W
Total Power Dissipation (Note 6)	T <sub>C</sub> = +25°C	P <sub>D</sub>	42.8	W
Thermal Resistance, Junction to Case (Note 6)		$R_{\theta JC}$	3.5	°C/W
Operating and Storage Temperature Range		T <sub>J,</sub> T <sub>STG</sub>	-55 to +175	°C

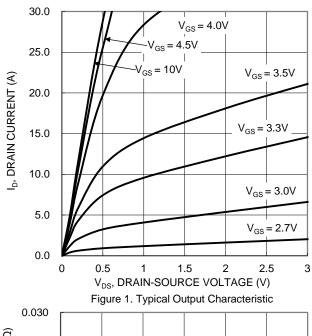
# Electrical Characteristics (@ T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	40	_	_	V	$V_{GS} = 0V$ , $I_D = 1mA$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	1	μA	V <sub>DS</sub> = 32V, V <sub>GS</sub> = 0V	
Gate-Source Leakage	I <sub>GSS</sub>	1	-	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)				<u> </u>			
Gate Threshold Voltage	V <sub>GS(th)</sub>	1	1.3	3	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$	
Static Drain-Source On-Resistance		_	11.8	15	m0	V <sub>GS</sub> = 10V, I <sub>D</sub> = 20A	
Static Drain-Source On-Resistance	R <sub>DS(on)</sub>		17.9	25	mΩ	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 15A	
Diode Forward Voltage	$V_{SD}$	1	0.9	1.2	V	$V_{GS} = 0V, I_{S} = 20A$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	Ciss	_	733	_	pF	.,	
Output Capacitance	Coss		235	_	pF	$V_{DS} = 20V, V_{GS} = 0V,$ f = 1MHz	
Reverse Transfer Capacitance	C <sub>rss</sub>	_	24	_	pF	1 = 11011112	
Gate Resistance	Rg	_	1.3	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge (V <sub>GS</sub> = 4.5V)	Qg	_	5.2	_	nC		
Total Gate Charge (V <sub>GS</sub> = 10V)	Qg	_	10.2	_	nC	), 20V I 20A	
Gate-Source Charge	Q <sub>gs</sub>	_	1.5	_	nC	$V_{DS} = 20V, I_{D} = 20A$	
Gate-Drain Charge	Q <sub>gd</sub>	_	3.1	_	nC	1	
Turn-On Delay Time	t <sub>D(on)</sub>	_	3.5	_	ns		
Turn-On Rise Time	t <sub>R</sub>		5.7	_	ns	$V_{DD} = 20V, V_{GS} = 10V,$	
Turn-Off Delay Time	t <sub>D(off)</sub>		8.7	_	ns	$R_G = 1.6\Omega, I_D = 20A$	
Turn-Off Fall Time	t <sub>F</sub>		1.8	_	ns	1	
Body Diode Reverse Recovery Time	t <sub>RR</sub>	_	11.9	_	ns	1. 454 174 40047	
Body Diode Reverse Recovery Charge	Q <sub>RR</sub>	_	9.28	_	$I_F = 15A$ , di/dt = 400A/ $\mu$ s		

 Device mounted on FR-4 substrate PC board, 2oz. copper, with thermal bias to bottom layer 1inch square copper plate.
 Thermal resistance from junction to soldering point (on the exposed drain pad).
 Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing. Notes:







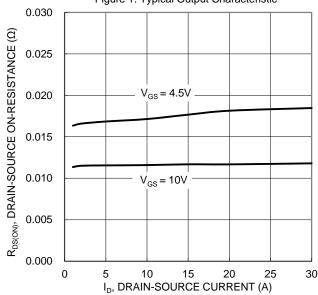


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

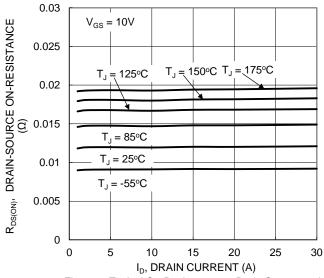


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

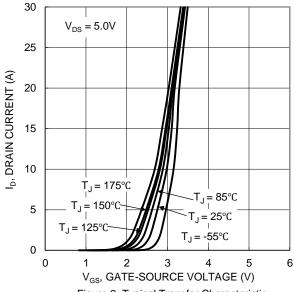


Figure 2. Typical Transfer Characteristic

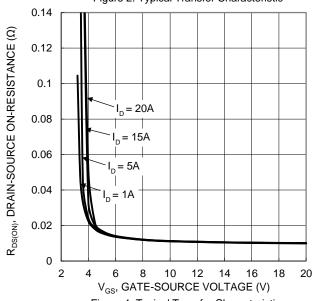


Figure 4. Typical Transfer Characteristic

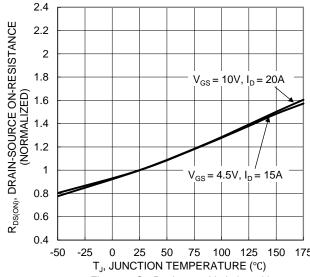


Figure 6. On-Resistance Variation with Temperature



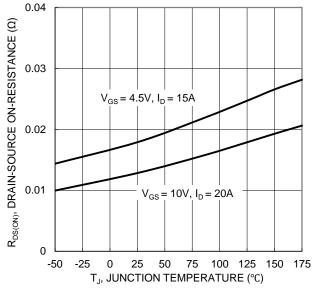


Figure 7. On-Resistance Variation with Temperature

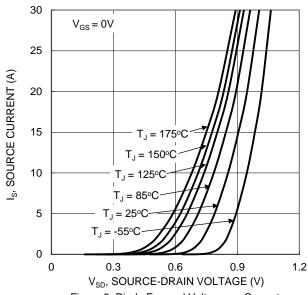


Figure 9. Diode Forward Voltage vs. Current

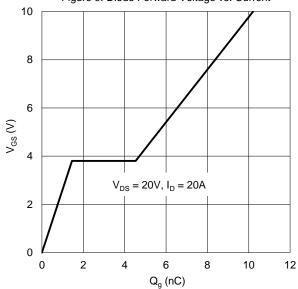


Figure 11. Gate Charge

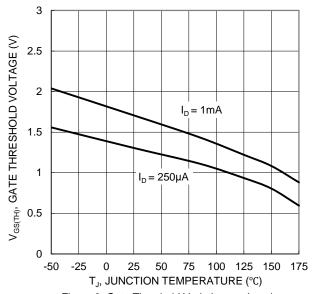


Figure 8. Gate Threshold Variation vs. Junction Temperature

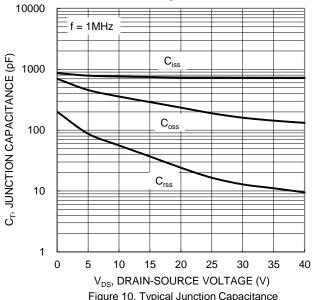


Figure 10. Typical Junction Capacitance

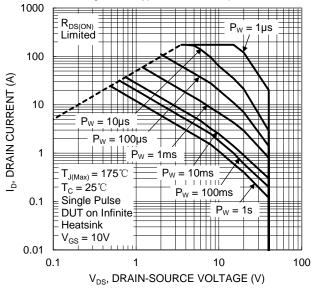


Figure 12. SOA, Safe Operation Area



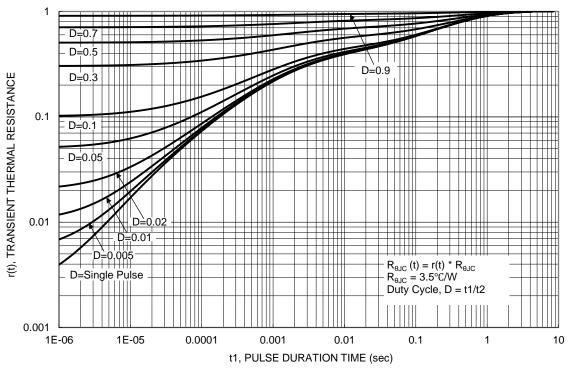


Figure 13. Transient Thermal Resistance

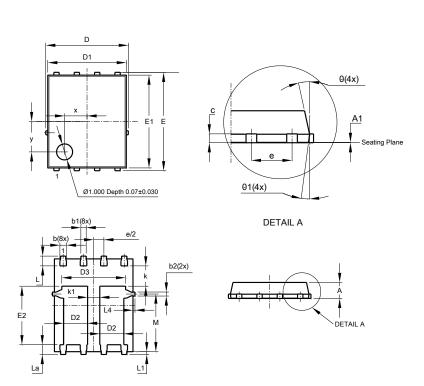


# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### Site1:

### PowerDI5060-8 (Type C)



Pow	PowerDI5060-8 (Type C)				
Dim	Min	Max	Тур		
Α	0.90	1.10	1.00		
A1	0	0.05	0.02		
b	0.33	0.51	0.41		
b1	0.300	0.366	0.333		
b2	0.20	0.35	0.25		
С	0.23	0.33	0.277		
D	5	.15 BS0	2		
D1	4.85	4.95	4.90		
D2	1.40	1.60	1.50		
D3	-	-	3.98		
Е	6	.15 BS0	2		
E1	5.75	5.85	5.80		
E2	3.56	3.76	3.66		
е	1.27BSC				
k	-	-	1.27		
k1	0.56	-	-		
L	0.51	0.71	0.61		
La	0.51	0.71	0.61		
L1	0.05	0.20	0.175		
L4	-	-	0.125		
М	3.50	3.71	3.605		
Х	-	-	1.400		
у	-	-	1.900		
θ	10°	12°	11°		
θ1	6°	8°	7°		
All Dimensions in mm					

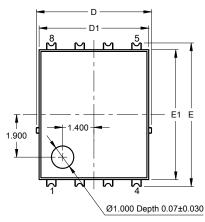


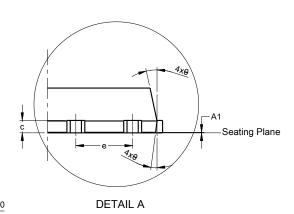
# Package Outline Dimensions (continued)

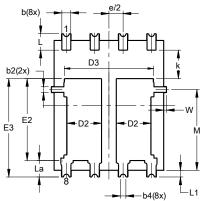
Please see http://www.diodes.com/package-outlines.html for the latest version.

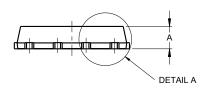
#### Site 2:

### PowerDI5060-8/SWP (Type UXD)









PowerDI5060-8/SWP					
(Type UXD)					
Dim	Min	Max	Тур		
Α	0.90	1.10	1.00		
A1	0.00	0.05			
b	0.30	0.50	0.41		
b2	0.20	0.35	0.25		
b4	C	).25REF			
С	0.230	0.330	0.277		
D	5	.15 BS0	)		
D1	4.70	5.10	4.90		
D2	1.46	1.66	1.55		
D3	3.78	4.18	3.98		
Е	6	.40 BS0	)		
E1	5.60	6.00	5.80		
E2	3.46	3.86	3.66		
E2a	4.195	4.595	4.395		
е	1	1.27BSC			
k	1.05				
L	0.635	0.835	0.735		
La	0.635	0.835	0.735		
L1	0.200	0.400	0.300		
М	3.205	4.005	3.605		
W	0.025	0.225	0.125		
θ	10°	12°	11°		
θ1	6°	8°	7°		
All Dimensions in mm					

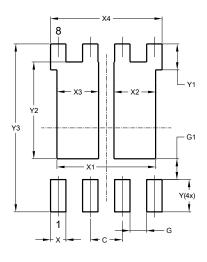


# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### Site 1:

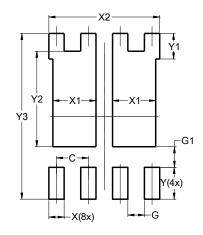
### PowerDI5060-8 (Type C)



Dimensions	Value (in mm)	
С	1.270	
G	0.660	
G1	0.820	
Χ	0.610	
X1	3.910	
X2	1.650	
Х3	1.650	
X4	4.420	
Υ	1.270	
Y1	1.020	
Y2	3.810	
Y3	6.610	

#### Site 2:

### PowerDI5060-8/SWP (Type UXD)



Dimensions	Value (in mm)	
С	1.270	
G	0.660	
G1	0.820	
Х	0.610	
X1	1.720	
X2	4.420	
Y	1.270	
Y1	1.020	
Y2	3.810	
Y3	6.610	



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